

# Initial Product/Process Change Notification Document #:IPCN22922X

Issue Date:27 Nov 2019

Title of Change:	Base and Submodule Substrate Change and Max Height Change for SB3229/SB3230/SB3231			
Proposed First Ship date:	27 May 2020 or earlier if approved by customer			
Contact Information:	Contact your local ON Semiconductor Sales Office or Christophe.Waelchli@onsemi.com			
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>.  Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.  Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>			
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN. Support@onsemi.com>			
Marking of Parts/ Traceability of Change:	Base substrate will change from white to a yellow/brown color. Affected products will be identified by workorder number.			
Change Category:	Assembly Change			
Change Sub-Category(s):	Material Change, Datasheet/Product Doc change			
Sites Affected:				
ON Semiconductor Sites	External Foundry/Subcon Sites			
ON Semiconductor Burlington, Canada	None			

## **Description and Purpose:**

This IPCN is to announce Base and Submodule Substrate Change and Max Height Change for SB3229/SB3230/SB3231.

	Before Change Description	After Change Description	
Base substrate	96% Al <sub>2</sub> 0 <sub>3</sub>	BT resin based laminate	
Submodule substrate	96% Al <sub>2</sub> 0 <sub>3</sub>	BT resin based laminate	
Max Body Height (Dim A2 in Datasheet)	1.651mm	1.422mm	
Max Overall Height (Dim A in Datasheet)	1.829mm	1.575mm	

There is no product marking change as a result of this change

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#### **Qualification Plan:**

**QV DEVICE NAME: SB3229-E1** 

RMS: 64169 PACKAGE: SiP-25

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	504 hrs
TC	JESD22-A104	Ta= -55°C to +125°C	100 cyc
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 4 @ 240°C	3x

Estimated date for qualification completion: 24 February 2020

### **List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
SB3229-E1	SB3229-E1
SB3229-E1-T	SB3229-E1
SB3230-E1-T	NA
SB3231-E1	NA
SB3231-E1-T	NA

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